

# GL -VIACLEAN95



## ADVANCED MELAMINE COATED HDF DRILL BACKER FOR CLEAN-HOLE PCB MANUFACTURING

WOOD FIBER HDF CONSTRUCTION WITH A LOW CONTENT MELAMINE RESIN FOR HIGH EFFICIENCY DRILL APPLICATIONS. DIMENSIONALLY STABLE AND EXCELLENT SURFACE FINISH LEAD TO CLEANER HOLES, MORE-EFFICIENT HIGH SPEED & ADVANCED MACHINING.

.095" +/- .005" THICKNESS: 37" X 49", 43" X 49", OR PRECUT AND TOOLED PANELS

### SPECIAL FEATURES:

- MINIMIZE BURRING – APPROVED SURFACE HARDNESS TO MINIMIZE COPPER BURRS ON DRILL EXIT.
- MINIMIZE RESIN SMEAR - THE CONSISTENT HIGH DENSITY CORE PROVIDES EXCELLENT DRILL CHIPPING AND CLEANING
- PROMOTES LONGER DRILL LIFE - HDF CHIP CLEANS EASILY FROM THE DRILL FLUTE TO AVOID BUILDUP AND TOOL BREAKAGE
- IMPROVED HOLE WALL QUALITY – CLEANER HOLES, NO CONTAMINANTS, MORE CONSISTENT RESULTS

### Technical Data

<b>Thickness and Tolerance</b>	2.45mm/ 0.095"	<b>Surface Hardness</b>	75 +/-5
<b>Thickness Swelling</b>	<35%	<b>Surface Finish</b>	Matte
<b>Moisture</b>	<7%	<b>Density</b>	90 0+/- 30Kg/m3
<b>Warpage</b>	<0.6% on diagonal	<b>Formaldehyde Release</b>	<0.3ppm
<b>Internal Bond Strength</b>	>1.8MPa	<b>MOR</b>	>Mpa

